

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3455898

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YASUYUKI SEKIMOTO	06/29/2015
HIDEKIYO TAKAOKA	07/01/2015
SHIGEO NISHIMURA	07/01/2015
MINORU UESHIMA	07/13/2015
TOHRU KURUSHIMA	07/05/2015
RECEIVING PARTY DATA	
Name:	MURATA MANUFACTURING CO., LTD.
Street Address:	10-1 HIGASHIKOTARI 1-CHOME
City:	NAGAKAKYO-SHI, KYOTO-FU
State/Country:	JAPAN
Postal Code:	617-8555
Name:	SENJU METAL INDUSTRY CO., LTD.
Street Address:	23 SENJUHASHIDOCHO
City:	ADACHI-KU, TOKYO
State/Country:	JAPAN
Postal Code:	120-8555
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14809533
CORRESPONDENCE DATA	
Fax Number:	(212)484-3990
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	2124843900
Email:	patentdocket@arentfox.com
Correspondent Name:	RICHARD LACAVA
Address Line 1:	1675 BROADWAY
Address Line 2:	ARENT FOX
Address Line 4:	NEW YORK, NEW YORK 10019

ATTORNEY DOCKET NUMBER:	036470.00050
NAME OF SUBMITTER:	RICHARD LACAVA
SIGNATURE:	/Richard LaCava/
DATE SIGNED:	07/27/2015
Total Attachments: 5 source=036470-00050ADS#page1.tif source=036470-00050ADS#page2.tif source=036470-00050ADS#page3.tif source=036470-00050ADS#page4.tif source=036470-00050ADS#page5.tif	

**DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN
APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

**Title of
Invention**

METHOD OF FORMING SOLDER BUMP, AND SOLDER BUMP

As the below named inventor, I declare that:

This declaration is directed to:

☒ The attached application, or

☐ United States application or PCT international application number _____
filed on _____

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the above-identified application, including the claims.

I acknowledge the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37 CFR 1.56, including for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT International filing date of the continuation-in-part application.

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I, as assignor, hereby sell, assign and set over to Murata Manufacturing Co., Ltd., having an address at 10-1, Higashikotari 1-chome, Nagaokakyo-shi, Kyoto-fu 617-8555, Japan; and Senju Metal Industry Co., Ltd., having an address at 23 Senjuhashidocho, Adachi-ku, Tokyo, 120-8555, Japan; as assignees, the entire right, title and interest for the United States and all other countries in and to all inventions disclosed and/or claimed in the above-identified application, all original, divisional, continuation, substitute or reissue applications and patents applied for or granted therefor in the United States and all other countries, including all rights of priority from the filing of said application, and all rights for past infringement, and the Commissioner of Patents and Trademarks is hereby authorized and requested to issue all patents on said inventions or resulting therefrom to said assignees herein, as assignees of the entire interest therein; and the undersigned for myself and my legal representatives, heirs and assigns do hereby agree and covenant without further remuneration, to execute and deliver all divisional, continuation, reissue and other applications for Patent on said inventions and all assignments thereof to said assignees or their assigns, to communicate to said assignees or their representatives all facts known to the undersigned respecting said inventions, whenever requested, to testify in any interferences or other legal proceedings in which any of said applications or patents may become involved, to sign all lawful papers, make all rightful oaths, and to do generally everything necessary to assist assignees, their successors, assigns and nominees to obtain patent protection for said inventions in the United States and all other countries, the expenses incident to said applications to be borne and paid by said assignees.

The undersigned hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

All statements made herein of my own knowledge are true, all statements made herein on information and belief are believed to be true, and further that these statements were made with the knowledge that willful false statements and the like are punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both, and may jeopardize the validity of the application or any patent issuing thereon.

LEGAL NAME OF INVENTOR

Inventor: Yasuyuki Sekimoto

Date: June 29, 2015

Signature: *Yasuyuki Sekimoto*

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LEGAL NAME OF INVENTOR

Inventor: Hidekiyo Takaka

Date: July 1, 2015

Signature: Hidekiyo Takaka

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LEGAL NAME OF INVENTOR

Inventor: Shigeo Nishimura

Date: July 1, 2015

Signature:

Shigeo Nishimura

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LEGAL NAME OF INVENTOR

Inventor: Minoru Ueshima

Date: July 13, 2015

Signature: Minoru Ueshima

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LEGAL NAME OF INVENTOR

Inventor: Tohru Kurushima

Date: July 5, 2015

Signature: Tohru Kurushima

AFDOCS/12183803.1